

Silicon Carbide Power Schottky Diode Chip

Features

- 1200 V Schottky rectifier
- 250 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F



Maximum Ratings at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V _{RRM}		1200	V
Continuous forward current	I _F	T _C ≤ 235 °C	1	А
RMS forward current	I _{F(RMS)}	T _C ≤ 235 °C	2	А
Operating and storage temperature	T _j , T _{stg}		-55 to 250	°C

Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Devemeter	Sympol	Conditions m		Values		11	
Parameter	Symbol			min.	typ.	max.	Unit
Diode forward voltage	V _F	I _F = 1 A, T _j = 2 I _F = 1 A, T _j = 2			1.96 3.1		V
Reverse current	I _R	V _R = 1200 V, T _j V _R = 1200 V, T _j =			0.1 6.6	10 30	μA
Total capacitive charge	Q _c	$ _{F} \leq _{F,MAX}$	V _R = 400 V V _R = 960 V		6 11		nC
Switching time	ts	dI _F /dt = 200 A/μs T _j = 210 °C	V _R = 400 V V _R = 960 V		< 17		ns
Total capacitance	С	$V_R = 1 V, f = 1 MHz$ $V_R = 400 V, f = 1 MHz$ $V_R = 1000 V, f = 1 MHz$	z, T _j = 25 °C		66 10 8		pF

Thermal resistance, junction - case	R _{thJC}	Assuming TO-276 package	3.55	°C/W

*For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).

Electrical Datasheet*

GB01SHT12-CAL

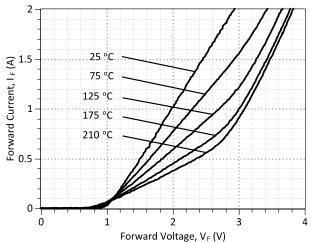


Figure 1: Typical Forward Characteristics

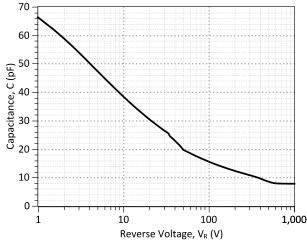


Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics

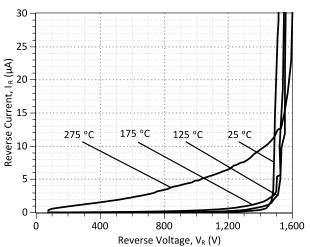
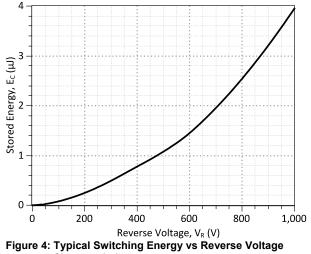


Figure 2: Typical Reverse Characteristics



Characteristics

Revision History					
Date	Revision	Comments	Supersedes		
2012/04/03	0	Initial release			

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB01SHT12-CAL device.

```
*
     MODEL OF GeneSiC Semiconductor Inc.
*
*
     $Revision: 1.0
                                $
*
                                $
     $Date: 05-SEP-2013
*
    GeneSiC Semiconductor Inc.
*
*
     43670 Trade Center Place Ste. 155
*
    Dulles, VA 20166
*
    httphttp://www.genesicsemi.com/index.php/sic-products/schottky
*
*
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     ALL RIGHTS RESERVED
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
* Start of GB01SHT12-CAL SPICE Model
.SUBCKT GB01SHT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0099); Temperature Dependant Resistor
D1 INT KATHODE GB01SHT12 25C; Call the 25C Diode Model
D2 ANODE KATHODE GB01SHT12 PIN; Call the PiN Diode Model
.MODEL GB01SHT12 25C D
+ IS
    1.88E-18
                                     0.9255
                          RS
+ N
         1
                                     98.29122743
                         IKF
         1.2
+ EG
                         XTI
                                     3
+ CJO
                                     0.367
         7.90E-11
                         VJ
+ M
         1.63
                         FC
                                     0.5
+ TT
        1.00E-10
1.00E-03
                          ΒV
                                     1500
+ IBV
                                    1200
                         VPK
+ IAVE
         1
                                    SiC Schottky
                          TYPE
      GeneSiC_Semiconductor
+ MFG
.MODEL GB01SHT12 PIN D
         2.76E-16
                                    0.84243
+ IS
                          RS
+ N
         3.791461
                                    2.98675
                         IKF
+ EG
         3.23
                         XTI
                                    30
+ FC
         0.5
                         TT
                                     0
+ BV
         1500
                         IBV
                                    1.00E-03
+ VPK
         1200
                          IAVE
                                     1
+ TYPE SiC PiN
.ENDS
* End of GB01SHT12-CAL SPICE Model
```